Electro-Thermal Interaction in Nanoscale Devices: Carbon Nanotubes and Phase-Change Memory

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http://nanoheat.stanford.edu/epop/research.html

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Joule (Self-Heating) in Electronics



http://phys.ncku.edu.tw/~htsu/humor/fry_egg.html

Thermal Management Methods



I believe that your CPU needs extra cooling but can I have just a little bit more space for food in the refrigerator?

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Thermal Management Methods



System Level → Active Microchannel Cooling (Cooligy)





Circuit + Software Level → active power management (turn parts of circuit on/off)

Transistor Level → electro-thermal device design

Chip-Level Thermal Network



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Chip-Level Thermal Trends



E. Pop et al., Proc. IEEE 94, 1587 (2006)

Sun surface: 6000 W/cm²

Device Level: Confined Geometries, Novel Materials



Material	k _{th} (W/m/K)
Si	148
Ge	60
Silicides	40
Si (10 nm)	13
SiO ₂	1.4

Thermal Resistance, Electrical Resistance



Thermal Resistance at Device Level



Sources: Mautry (1990), Bunyan (1992), Su (1994), Lee (1995), Jenkins (1995), Tenbroek (1996), Jin (2001), Reyboz (2004), Javey (2004), Seidel (2004), Pop (2004-6), Maune (2006).

Carbon Nanotubes for Electronics

Carbon nanotube = rolled up graphene sheet

Great electrical & thermal conductors

- Semiconducting → transistors
- Metallic → interconnects
- $\sigma pprox 100 \ x \ \sigma_{Cu}$; k $pprox k_{Diamond}$

• (Some) open questions:

Thermal conductivity of single-walled carbon nanotubes (SWNTs)

Great thermal conductivity k, low thermal conductance (small d)

- Optimizing high-field transport

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Back-of-the-Envelope Estimates

E. Pop et al., Phys. Rev. Lett. 2005; Proc. IEDM 2005

- Typical *L* ~ 2 μm, *d* ~ 2 nm
- <u>On insulating solid substrate</u>
- Heat dissipated into substrate
 - Moderate power ~ 10 $\mu W/\mu m$
 - Peak ∆T ~ 60 K
- Thermal conductivity k ~ 3000 W/m/K
- Freely suspended nanotube
- Heat dissipated along tube length
 - Moderate power ~ 10 μ W (10 μ A @ 1 V)
 - Peak ∆T ~ 400 K!







Transport in Suspended Nanotubes

E. Pop et al., Phys. Rev. Lett. 95, 155505 (2005)



- Observation: significant current degradation and negative differential conductance at high bias in suspended tubes
- <u>Question</u>: Why? <u>Answer</u>: Tube gets HOT (how?)



• Evidence for much longer phonon lifetimes in suspended SWNTs:

- Narrower Raman linewidths of suspended tubes (Dresselhaus in APL '04)
- Observed 50x lifetime for suspended RBM mode (Dekker in Nature '04)
- Why? Substrate interface provides phonon relaxation channels
- Consequence: hot optical phonons in suspended SWNTs under high bias

Quick Recap of Phonons



• "Hot phonons" = highly occupied modes above room temperature

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Phonons and Guitar Strings



- Phonons = quantized lattice vibrations
- Transverse $(u \perp k)$ vs. longitudinal modes $(u \parallel k)$, acoustic vs. optical
- "Hot phonons" = highly occupied modes above room temperature

Transport Model Including Hot Phonons



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All Suspended Tubes Exhibit NDC

E. Pop et al., Phys. Rev. Lett. 95, 155505 (2005)



- First experimental observation of Negative Differential Conductance (NDC)
 - ALL suspended tubes show NDC; longest at fields as low as 200 V/cm
 - Previous work predicts velocity saturation at *E-fields* > 5 kV/cm (isothermal)
- Peak current: $I_{max} \sim 1/L$, which scales as the *thermal conductance*
 - Compare to I_{max} > 20 μ A for same L tubes on substrate

Effect of κ_{th} at High Temperature, Bias



- Current at high bias: $I \sim \lambda_{op} \sim 1/N_{op} \sim 1/T \sim \kappa_{th}$
- Thermal conductivity $\underline{\kappa}_{th} \sim 1/T$ at high T (Umklapp phonon scattering)
- *I-V* curve at high bias indirectly measures $\kappa_{th}(T)$ at high T !
- Back out to $T \sim 300 \text{ K} \rightarrow \kappa_0 \sim 3600 \text{ W/m/K}$

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Extracting SWNT Thermal Conductivity

E. Pop et al., Nano Letters 6, 96 (2006)



- Numerical extraction of k from the high bias (V > 0.3 V) tail
- Subtle second-order effect of three-phonon scattering introduces 1/T² temperature dependence (N. Mingo, NL Jun'05)
- Comparison to data from 100-300 K of UT Austin group (C. Yu, NL Sep'05)
- <u>Result</u>: first "complete" picture of SWNT thermal conductivity from 100 800 K

Gas Environment Dependence of NDC

D. Mann et al., J. Phys. Chem. B 110, 1502 (2006)



- Current enhancement (△I) in ambient gases does not scale with thermal conductivity of gas
- It scales with the number of atoms in the physisorbed gas molecules
- Physisorbed gases act like "weak substrates" for suspended SWNTs, providing more vibrational modes for OP decay

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Effects of Extreme Environment

D. Mann et al., J. Phys. Chem. B 110, 1502 (2006)



- If the surrounding molecules are dense enough, they act as a substrate, dissipating heat and relaxing optical phonons
- Environment can be engineered to modify properties of devices

Light Emission from Suspended SWNTs D. Mann et al., Nature Nano (2007)





Return to SWNTs On Substrates

E. Pop et al., Proc IEDM 2005; Proc IEEE 2006

- SWNT on insulating solid substrate •
- Heat dissipated into substrate rather than along tube length
- What is the heat loss coefficient *g*? •
- [A: need some gauge of the tube temperature]



Nanotube Temperature Gauge



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Nanotube Temperature Gauge

- Doesn't exist
- But... oxidation (burning) temperature is known



Breakdown of SWNTs in Air (Oxygen)



- Thermogravimetric (TGA) data shows SWNTs exposed to air break down by oxidation at 500 < T_{BD} < 700 °C (800–1000 K)
- Joule breakdown voltage data shows V_{BD} scales with L in air
- Supports cooling mechanism along the length, into the substrate

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Breakdown of SWNTs: Analysis

E. Pop et al., Proc. IEDM (2005)

$$A\nabla(k\nabla T) + p' - g(T - T_0) = 0$$

At breakdown: $p' = I_{BD}V_{BD} / L$

$$V_{BD} = gL(T_{BD} - T_0)/I_{BD}$$



- For on-substrate tubes, empirically note that:
 - $-V_{BD}$ vs. L in air scales linearly, as about 5 V/µm
 - Breakdown currents for L > 1 μ m always around $I_{BD} \approx$ 20 μ A
- Analytic solution of heat conduction equation
 - Heat loss per unit length: $g \approx 0.17 \pm 0.03$ WK⁻¹m⁻¹
- No assumption was made about electrical transport model

Electro-Thermal Model for m-SWNTs

E. Pop et al., Proc. IEDM (2005)



- Same model as that used for suspended SWNTs
- Include Joule heating, couple with heat conduction equation
- Self-consistent solution $A\nabla(k\nabla T) + p' g(T T_0) = 0$
- · No assumptions of hot phonons needed

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Modeling Long SWNTs up to Breakdown

E. Pop et al., submitted to JAP, pre-print cond-mat/0609075



- Thermal "healing length" along SWNT ~ 0.25 μm
- Current saturation ~ 20 μ A in long tubes (> 1 μ m) due to self-heating
- Self-heating not significant when $p' < 5 \mu W/\mu m$ (design goal?)

Some Notes on Shorter SWNTs



- Thermal "healing length" along SWNT ~ 0.2 μm
- Current saturation ~ 20 μA in long tubes (> 1 $\mu m)$ due to self-heating
- Self-heating not significant when $p' < 5 \mu W/\mu m$ (design goal?)
- In short (< 1 μm) tubes current enhancement (> 20 μA) very likely aided by Joule heating shifting towards the contacts

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From Nanotubes to Phase-Change Memory



What Is Phase-Change Memory?



- PCM: Like Flash memory (non-volatile)
- PCM: Unlike Flash memory (resistance change, not charge storage)
- Faster than Flash (100 ns vs. 0.1–1 ms), smaller than Flash (which is limited by ~1000 electrons stored/bit)
- For: iPod nano, mobile phones, PDAs, solid-state hard drives...

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How Phase-Change Memory Works



- Based on Ge₂Sb₂Te₅ reversible phase change: R_{amorph} / R_{xtal} > 100
- Short (10 ns), high pulse (0.5 mA) melts, amorphizes GST
- Longer (100 ns), lower pulse (0.1 mA) crystallizes GST
- Small cell area (sits on top of heater), challenge is reliability and lowering programming current (BUT, helped by scaling!)

Samsung 512 Mb PCM Prototype

Sep 11, 2006



Put in perspective: NAND Flash chips of 8+ Gb in production

"Samsung completed the first working prototype of what is expected to be the main memory device to replace high density Flash in the next decade – a Phase-change Random Access Memory (PRAM). The company unveiled the 512 Mb device at its sixth annual press conference in Seoul today." Source:

http://samsung.com/PressCenter/PressRelease/PressRelease.asp?seq=20060911_0000286481

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Intel/ST Phase-Change Memory Wafer

Sep 28, 2006



"Intel CTO of Flash Memory Ed Doller holds the first wafer of 128 Mbit phase change memory (PCM) chips, which has just been overnighted to him from semiconductor maker STMicroelectronics in Agrate, Italy. Intel believes that PCM will be the next phase in the non-volatile memory market." Source: <u>http://www.eweek.com/article2/0,1895,2021841,00.asp</u>



- Phase change physics thermal and temporal evolution
- (Practical goal: memory cell with lower programming current)

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GST Thermal Conductivity and Interface

J. Reifenberg et al., ITHERM 2006





- GST thermal conductivity 0.2–1.0 W/m/K (SiO₂ ~ 1.3 W/m/K)
- Thermal interface resistance (TIR) ≈ equivalent to 10-20 nm GST
- TIR alters temperature profile and may be key to device operation

AC and DC Thermal Measurements



- AC harmonic heating of thin GST films (3-ω method)
 - 35-70-140 nm thin GST films, capped by SiO_2
- DC electrical thermometry of electrode metals
 - Transport physics (electrical, thermal) in *amorphous materials*

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Conclusions

Summary:

- · Self-heating due to small dimensions or thermal insulation
- HOT metallic single-wall carbon nanotubes at high bias:
 - Hot phonons and thermal conductivity of SWNTs
 - Light emission and breakdown (burning) of SWNTs in air
- Role of interface thermal resistance and material properties (amorphous vs. crystalline) in phase-change memory

Publications (see http://nanoheat.stanford.edu/epop/research.html)

- E. Pop, D. Mann, J. Cao, Q. Wang, K. Goodson, H. Dai, *Phys. Rev. Lett.* **95**, 155505 (2005)
- E. Pop, D. Mann, J. Reifenberg, K. Goodson, H. Dai, Proc. IEDM, Washington DC (2005)
- J. Reifenberg, E. Pop, A. Gibby, S. Wong and K. Goodson, *ITHERM* 106 (2006)
- D. Mann, E. Pop, Q. Wang, K. Goodson, H. Dai, J. Phys. Chem. B 110, 1502 (2006)
- E. Pop, D. Mann, Q. Wang, K. Goodson, H. Dai, Nano Letters 6, 96 (2006)
- D. Mann et al., to appear in Nature Nano (2007)

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